

SLOVENSKI STANDARD
SIST EN 60749-32:2004/A1:2010
01-november-2010

**Polprevodniški elementi - Metode za mehansko in klimatsko preskušanje - 32. del:
Vnetljivost elementov v plastičnih okrovih (z zunanjim plamenom) - Dopolnilo A1
(IEC 60749-32:2002/A1:2010)**

Semiconductor devices - Mechanical and climatic test methods - Part 32: Flammability of plastic-encapsulated devices (externally induced) (IEC 60749-32:2002/A1:2010)

Halbleiterbauelemente - Mechanische und klimatische Prüfverfahren - Teil 32:
Entflammbarkeit von Bauelementen in Kunststoffgehäusen (Fremdentzündung) (IEC
60749-32:2002/A1:2010) **(standards.iteh.ai)**

Dispositifs à semiconducteurs - Methodes d'essais mécaniques et climatiques - Partie
32: Inflammabilité des dispositifs à encapsulation plastique (cas d'une cause extérieure
d'inflammation) (CEI 60749-32:2002/A1:2010)

Ta slovenski standard je istoveten z: EN 60749-32:2003/A1:2010

ICS:

13.220.40	Sposobnost vžiga in obnašanje materialov in proizvodov pri gorenju	Ignitability and burning behaviour of materials and products
31.080.01	Polprevodniški elementi (naprave) na splošno	Semiconductor devices in general

SIST EN 60749-32:2004/A1:2010 en

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SIST EN 60749-32:2004/A1:2010

<https://standards.iteh.ai/catalog/standards/sist/36bd7dd8-e2c2-4020-a919-57563bdea582/sist-en-60749-32-2004-a1-2010>

EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN 60749-32/A1

September 2010

ICS 31.080.01

English version

**Semiconductor devices -
Mechanical and climatic test methods -
Part 32: Flammability of plastic-encapsulated devices (externally induced)
(IEC 60749-32:2002/A1:2010)**

Dispositifs à semiconducteurs -
Méthodes d'essais mécaniques
et climatiques -
Partie 32: Inflammabilité des dispositifs
à encapsulation plastique (cas
d'une cause extérieure d'inflammation)
(CEI 60749-32:2002/A1:2010)

Halbleiterbauelemente -
Mechanische und klimatische
Prüfverfahren -
Teil 32: Entflammbarkeit
von Bauelementen in Kunststoffgehäusen
(Fremdentzündung)
(IEC 60749-32:2002/A1:2010)

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This amendment A1 modifies the European Standard EN 60749-32:2003; it was approved by CENELEC on 2010-09-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this amendment the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This amendment exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Bulgaria, Croatia, Cyprus, the Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Romania, Slovakia, Slovenia, Spain, Sweden, Switzerland and the United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Management Centre: Avenue Marnix 17, B - 1000 Brussels

Foreword

The text of document 47/2018/CDV, future amendment 1 to IEC 60749-32:2002, prepared by IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as amendment A1 to EN 60749-32:2003 on 2010-09-01.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CEN and CENELEC shall not be held responsible for identifying any or all such patent rights.

The following dates were fixed:

- latest date by which the amendment has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2011-06-01
- latest date by which the national standards conflicting with the amendment have to be withdrawn (dow) 2013-09-01

Annex ZA has been added by CENELEC.

Endorsement notice

The text of amendment 1:2010 to the International Standard IEC 60749-2:2002 was approved by CENELEC as an amendment to the European Standard without any modification.

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[SIST EN 60749-32:2004/A1:2010](https://standards.iteh.ai/catalog/standards/sist/36bd7dd8-e2c2-4020-a919-57563bdea582/sist-en-60749-32-2004-a1-2010)

<https://standards.iteh.ai/catalog/standards/sist/36bd7dd8-e2c2-4020-a919-57563bdea582/sist-en-60749-32-2004-a1-2010>

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
<i>Replace the existing reference:</i>				
IEC 60695-2-2	1991	Fire hazard testing - Part 2: Test methods - Section 2: Needle-flame test	EN 60695-2-2 ¹⁾	1994
<i>with the following new reference:</i>				
IEC 60695-11-5	2004	Fire hazard testing - Part 11-5: Test flames - Needle-flame test method - Apparatus, confirmatory test arrangement and guidance	EN 60695-11-5	2005

¹⁾ EN 60695-2-2 is superseded by EN 60695-11-5:2005, which is based on IEC 60695-11-5:2004.

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IEC 60749-32

Edition 1.0 2010-07

INTERNATIONAL STANDARD

NORME INTERNATIONALE

AMENDMENT 1
AMENDEMENT 1

**Semiconductor devices – Mechanical and climatic test methods –
Part 32: Flammability of plastic-encapsulated devices (externally induced)**
(standards.iteh.ai)

**Dispositifs à semiconducteurs – Méthodes d'essais mécaniques et climatiques –
Partie 32: Inflammabilité des dispositifs à encapsulation plastique (cas d'une
cause extérieure d'inflammation)**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

COMMISSION
ELECTROTECHNIQUE
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ICS 31.080.01

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FOREWORD

This amendment has been prepared IEC technical committee 47: Semiconductor devices.

The text of this amendment is based on the following documents:

CDV	Report on voting
47/2018/CDV	47/2061/RVC

Full information on the voting for the approval of this amendment can be found in the report on voting indicated in the above table.

The committee has decided that the contents of this amendment and the base publication will remain unchanged until the stability date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

iTeh STANDARD PREVIEW (standards.iteh.ai)

2 Normative references

[SIST EN 60749-32:2004/A1:2010](https://standards.iteh.ai/catalog/standards/sist/36bd7dd8-e2c2-4020-a919-57563bdea582/sist-en-60749-32-2004-a1-2010)

Replace the existing reference: <https://standards.iteh.ai/catalog/standards/sist/36bd7dd8-e2c2-4020-a919-57563bdea582/sist-en-60749-32-2004-a1-2010>

IEC 60695-2-2:1995, *Fire hazard testing – Part 2: Test methods – Section 2: Needle-flame test*

with the following new reference:

IEC 60695-11-5:2004, *Fire hazard testing – Part 11-5: Test flames – Needle-flame test method – Apparatus, confirmatory test arrangement and guidance*

3 Test procedure

In Item c) and Item d) change references 'as per Figure 1b of IEC 60695-2-2' to 'according to Figure 1b of IEC 60695-11-5:2004'.

In Item e) change the reference 'clause 4 of IEC 60695-2-2' to 'according to 5.4 of IEC 60695-11-5:2004'
